

# SOT700-1

plastic low profile ball grid array package; 156 balls; body 15 x 15 x 1.05 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LBGA156
<b>Package type industry code</b>	LBGA156
<b>Package style descriptive code</b>	LBGA (low profile ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-192
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	6-11-2001

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	14.8	-	15	15.2	mm
E	package width	14.8	-	15	15.2	mm
A	seated height	[tbd]	-	1.65	1.65	mm
A <sub>2</sub>	package height	0.95	-	1.05	1.2	mm
n <sub>2</sub>	actual quantity of termination	-	-	156	-	



2. Package outline

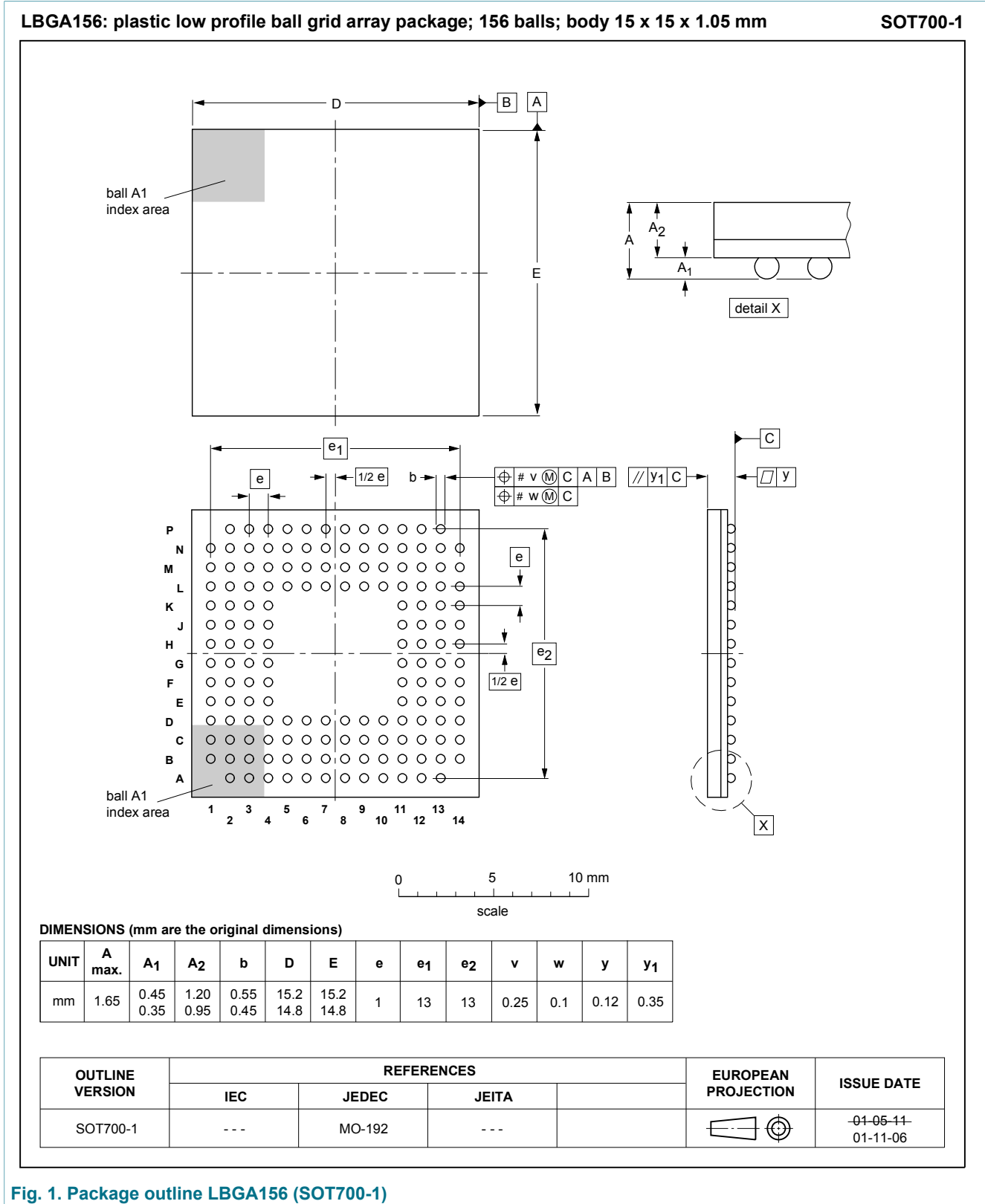


Fig. 1. Package outline LPGA156 (SOT700-1)

### 3. Soldering

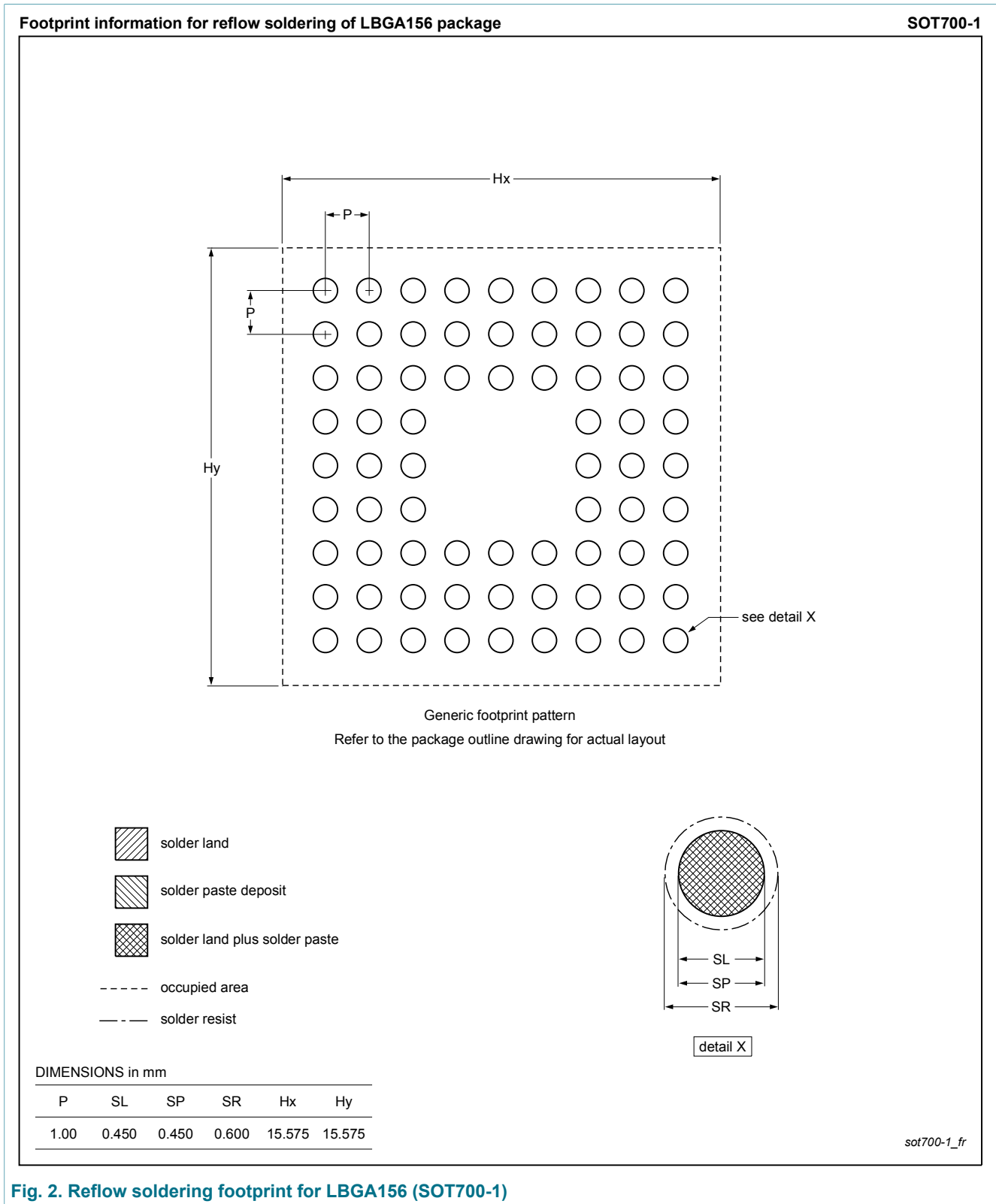


Fig. 2. Reflow soldering footprint for LBG156 (SOT700-1)

## 4. Legal information

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Date of release: 8 February 2016

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